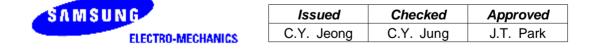
Date : 2004.11.19 No. : H26.00 Rev. : Preliminary

VC-TCXO SPECIFICATION

| Customer | ZTE |
|------------------|-------------------------------------|
| Customer Model | |
| Туре | 3225 26MHz VC-TCXO |
| Samsung Part No. | TOH2600DPI4CNP - Preliminary |



SAMSUNG ELECTRO-MECHANICS CO., LTD

314, Metan3-dong, Yeongtong-Gu, Suwon, Gyunggi-do, Korea 443-743 TEL : 82-31-210-5672 FAX : 82-31-210-6554

Contents

| 1. Construction Of Part No. | 1/5 |
|-------------------------------------------|-----|
| 2. Electrical Characteristics | 1/5 |
| 3. Environmental Characteristics | 2/5 |
| 4. Measurement Circuit (VC-TCXO) | 2/5 |
| 5. Outline (3225 VC-TCXO) | 3/5 |
| 6. Recommended Reflow Soldering Condition | 4/5 |
| 7. Caution to handle / storage | 4/5 |
| 8. Component Packing (3225) | 5/5 |

Revision Record

| Rev | Date | Page | Contents | Remarks |
|-----|------|------|----------|---------|
| | | | | |
| | | | | |
| | | | | |
| | | | | |
| | | | | |
| | | | | |
| | | | | |
| | | | | |
| | | | | |
| | | | | |
| | | | | |

1/5

1. Construction Of Part No.

example TO H XXXX D P H 4 K R A a b c d e f g h

| No | Meaning | No.of Digits | Example |
|----|-----------------------|--------------|----------------------------------------------------------------------------------------------|
| а | Name Of Product | 2 | TO : Temperature Compensated Crystal Oscillator |
| b | Size Of Product | 1 | B : 5.0x3.2x1.5 mm F : 4.0x2.5x1.2 mm H : 3.2x2.5x1.2 mm C : User Spec |
| С | Nominal Frequency | 4 | XXXX : XX.XX00000 MHz |
| d | Addtional Function | 1 | N: No Additional Function D: Digital Temperature Compensation M: Multi-Output Function |
| е | Operating Voltage | 1 | A: 3.0V D: 5.0V G:2.4V P: User Spec |
| f | Operating Temperature | 1 | H : -30℃ ~ 80℃ I : -30℃ ~ 75℃ J : -30℃ ~ 70℃ K : -20℃ ~ 70℃ L : 0℃ ~ 50℃ M : User Spec |
| g | Pin Number | 1 | 4 : 4 pin |
| h | User Serial Number | 3 | |

2. Electrical Characteristics

| Parameter | Value | Condition | |
|-----------------------------|-------------------------------------|--------------------------|--|
| Output Frequency | 26.000000MHz | | |
| Supply Voltage | DC 2.8V +/-5% | | |
| Output Level | 0.8 Vp-p Min (Clipped Sine Wave) | 10kohm//10pF +/-10% each | |
| Current Drain | 1.5 mA Max | 10kohm//10pF +/-10% each | |
| Operating Temperature Range | -30'C to +75'C | | |
| Storage Temperature Range | -40'C to +85'C | | |
| Frequency Stability | | | |
| vs. Temperature | +/-2.5ppm Max | Referenced to 25'C | |
| vs. Supply Voltage | +/-0.3ppm Max | DC 2.8V +/-5% | |
| vs. Load | +/-0.2ppm Max | 10kohm//10pF +/-10% each | |
| vs. Aging | +/-1.0ppm Max | 1 Year | |
| Frequency Tolerance | | | |
| Initial | +/-1.5ppm Max | Vcont=1.5V, T=25'C+/-2'C | |
| After Reflow | +/-2.5ppm Max | Vcont=1.5V, T=25'C+/-2'C | |
| AFC-Characteristic | | | |
| Vcont=2.5V | +9 to +15ppm | Deferenced to Moont 4.5% | |
| Vcont=0.5V | -15 to -9ppm | Referenced to Vcont=1.5V | |

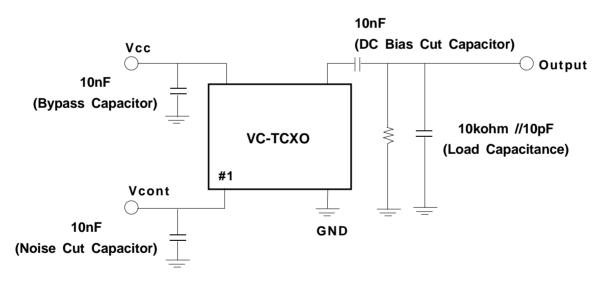
3. Environmental Characteristics

| No | Test Item | Test Condition | |
|----|------------------------------------|--------------------------------------------------------------------------|--|
| 1 | High Temp. Storage | 85+/-2'C, 96+/-2Hr | |
| 2 | Low Temp. Storage | -40+/-2'C, 96+/-2Hr | |
| 3 | High Temp. & High Humidity Storage | 40'C, 90~95%RH, 96+/-2Hr | |
| 4 | Thermal shock | -40'C/30min ~ 85'C/30min, 15cycles | |
| 5 | Vibration | Frequency : 20~2000Hz Acceleration : 5G XYZ each direction × 30min | |
| 6 | Drop | 150cm, 120g Jig, onto concrete, each side(6), corner(1), total 7times | |
| 7 | Solderability | lity 230°C+/-5°C for 10sec, more than 90% must be covered | |

1. Must be measured after 4~12hours at room temperature, humidity.

2. Frequency must be within initial value +/-2ppm.

4. Measurement Circuit (VC-TCXO)

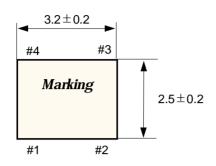


✗ Note

- 1. Be cautious of VC-TCXO pin connection.
- 2. Load Capacitance includes probe and test JIG capacitance.

5. Outline (3225 VC-TCXO)

Top View



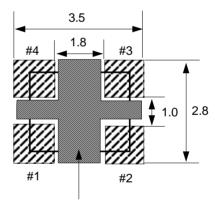
| Lead No. | Connection |
|----------|------------|
| #1 | Vcont |
| #2 | GND |
| #3 | Output |
| #4 | Vcc |

3/5

Side View

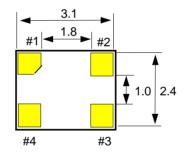


Recommended Land Pattern (3225 Type)



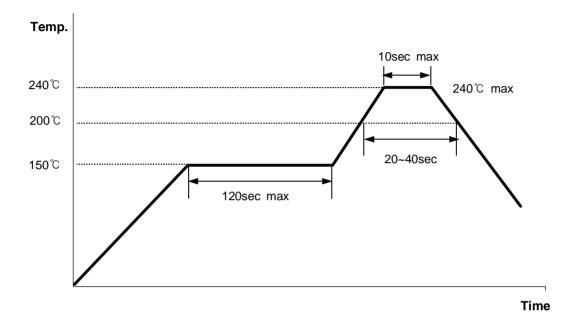
Do not design any patterns except GND in this area

Bottom View



6. Recommended Reflow Soldering Condition

Pre heating temperature : 150'C (120sec max) Heating temperature : 240'C max (10sec max)



7. Caution to handle / storage

1. Storage

Keep products at the room temperature ($20\pm15^{\circ}$ C), normal humidity (below 60% RH), recommend to use products within 6months after manufacturing, and in case of opening the product box, recommend to use products within 24 hours.

2. Static Electricity

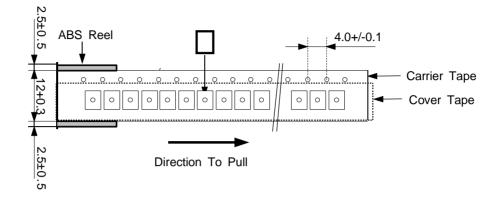
While handling, prevent to occur static electricity, and while moving, move products under doing - no static electricity.

3. Reflow

Recommend to soldering according to recommended reflow condition.

- 4. General items
 - After thermal shock and reflow process, wait for 2 hours Min, and test.
 - Be cautious of over-pressure on the product, it can be happened to crack.
 - Be cautious of product pin connection.
 - Be cautious of invasion of outside material (like underfill), due to this, it can be effected to product.
 - In using hot-gun for repair, be cautious of over-heat, separation of product.

8. Component Packing (3225)



- After inserting products into the carrier tape, and then it is rolled up to ABS reel under the shielding condition of carrier covering tape. Direction to pull is shown on the above drawings.
- 2. Both the end edge, 160mm of carrier tape will be shield without products.
- 3. Degree of detaching strength of carrier tape
 - (1) Angle : 165°~ 185°
 - (2) Speed : 300mm/min (5mm/Sec.)
 - (3) Force : 20g ~70g

